

EEPROM

NAND

Etron



winbond

ADVANTECH

INELTEK OFFER

- We bring the latest innovations to kick-start your projects
- Our application team supports your developers
- We facilitate access to vendor experts to enhance your development
- We offer you a stable supply chain for production

NOR



goodram



DRAM

SRAM



ABOUT INELTEK

- Founded in 1987
- Headquarters in Heidenheim (Germany)
- 2 global warehouse locations in Germany & China
- 8 European sales offices plus USA, Hongkong & Shenzhen
- Almost 4 decades of design-in experience
- All time committed to innovation
- Flexible & independent mindset to serve your demands & global logistic needs
- 55+ Suppliers for electronic components & solutions
- Long-term relationships with suppliers and experts
- Excellent technical support

Version 092026



AMIC

- Density: 128 kb - 512 Mb
- V_{CC}: 1.65V - 5.5V
- Interface: Parallel, SPI, QSPI
- max. Temp. Range: -40/+85°C
- X-Ref to Spansion, Micron, Macronix
- Company: Taiwanese, fabless

WINBOND

- Density: 1 Mb - 2 Gb
- V_{CC}: 1.2V - 3.6V
- Interface: SPI, QSPI, Octal
- max. Temp. Range: -40/+125°C
- Security Flash CC EAL2+ (PQC ready)
- Company: Taiwanese, own Fabs

PYRAMID

- Density: 1 Mb - 4 Mb
- V_{CC}: 5.0V +/- 10%
- Interface: Parallel
- max. Temp. Range: -55/+125°C
- MIL-STD-883 Class B option
- Company: US based, fabless

BYTE SEMICONDUCTOR

- Density: 512 kb - 2 Gb
- V_{CC}: 1.65V - 3.6V
- Interface: Parallel, SPI, QSPI
- max. Temp. Range: -40/+125°C
- Special Low Power Flash (SONOS, 55nm)
- Company: US based, fabless

XSEMITRON

- Density: 2 Mb - 1 Gb
- V_{CC}: 1.65V - 3.6V
- Interface: QSPI
- max. Temp. Range: -40/+125°C
- Small Package Options
- Company: Chinese, fabless



ADVANTECH

- Density: 2 GB - 30.7 TB
- Interface: eMMC, PCIe, SATA, SD, CF
- max. Temp. Range: -40/+85°C
- Focus on AI, Rugged & High-Reliability
- Company: Taiwanese

INTELLIGENT MEMORY

- Density: 1 GB - 2 TB
- Interface: eMMC, PATA, PCIe, SATA, SD, UFS, USB
- max. Temp. Range: -40/+105°C
- Automotive Grade 2 Options
- Company: Taiwanese, fabless

WINBOND

- Density: 512 Mb - 8 Gb
- V_{CC}: 1.8V - 3V
- Interface: QSPI, Octal, ONFI
- max. Temp. Range: -40/+115°C
- Security NAND & Automotive Grade
- Company: Taiwanese, own Fabs

XSEMITRON

- Density: 1 Gb - 8 Gb
- V_{CC}: 1.7V - 3.6V
- Interface: Parallel, QSPI, SD
- max. Temp. Range: -40/+85°C
- eMMC up to -25/+85°C
- Company: Chinese, fabless

ETRON

- Density: 512 Mb - 128 GB
- V_{CC}: 1.8V - 3.3V
- Interface: SPI, eMMC
- max. Temp. Range: -40/+85°C
- Company: Taiwanese, fabless

SILICONMOTION

- Density: 8 GB - 960 GB
- Interface: eMMC, PCIe, SATA, UFS
- max. Temp. Range: -40/+105°C
- Focus on AI and Automotive
- Company: Taiwanese, fabless

UDINFO

- Density: 2 GB - 7.68 TB
- Interface: eMMC, PATA, PCIe, SATA, SD, UFS
- max. Temp. Range: -40/+85°C
- FIPS 140-2 & FIPS 140-3 Options
- Company: Taiwanese, fabless

LONGSYS

- Density: 4 GB - 512 GB
- Interface: eMMC, UFS
- max. Temp. Range: -40/+105°C
- Automotive Options
- Company: Chinese, fabless



ADVANTECH

- Density: 512 MB - 128 GB
- Type: DDR3, DDR4, DDR5
- Formfactor: Module
- max. Temp. Range: -40/+125°C
- Company: Taiwanese

AMIC

- Density: 512 Mb
- Type: SDRAM
- Formfactor: IC
- max. Temp. Range: -40/+85°C
- Company: Taiwanese, fabless

GOODRAM

- Density: 2 GB - 96 GB
- Type: DDR4, DDR5
- Formfactor: Module
- Company: Taiwanese, fabless

INTELLIGENT MEMORY

- Density: 32 Mb - 32 GB
- Type: SDRAM, DDR, DDR2, DDR3, (LP)DDR4, DDR5
- Formfactor: IC, Module
- max. Temp. Range: -40/+125°C
- Company: Taiwanese, fabless

WINBOND

- Density: 16 Mb - 16 Gb
- Type: (LP)SDRAM, (LP)DDR, (LP)DDR2, (LP)DDR3, (LP)DDR4
- Formfactor: IC
- max. Temp. Range: -40/+125°C
- Company: Taiwanese, own Fabs

ZENTEL

- Density: 512 Mb - 8 Gb
- Type: SDRAM, DDR, DDR2 (LP)DDR3, DDR4
- Formfactor: IC
- max. Temp. Range: -40/+125°C
- Company: Taiwanese, fabless

ETRON

- Density: 16 Mb - 32 Gb
- Type: SDRAM, DDR, (LP)DDR2, DDR3, (LP)DDR4, RPC
- Formfactor: IC, KGD
- max. Temp. Range: -40/+105°C
- Company: Taiwanese, fabless

LONGSYS

- Density: 2 Gb - 192 GB
- Type: DDR3, (LP)DDR4, (LP)DDR5
- Formfactor: IC, DIMM, CAMM2, CLX
- max. Temp. Range: -40/+85°C
- Company: Chinese, fabless

XSEMITRON

- Density: 2 Gb - 8 Gb
- Type: DDR3, (LP)DDR4
- Formfactor: IC
- max. Temp. Range: -40/+105°C
- Company: Chinese, fabless

UDINFO

- Density: 2 GB - 64 GB
- Type: DDR3, DDR4, DDR5
- Formfactor: Module
- max. Temp. Range: -40/+85°C
- Company: Taiwanese, fabless

Version 092026



SRAM

AMIC

- Density: 64 kb - 8 Mb
- V_{CC}: 3V / 5V
- Interface: x8, x16
- max. Temp. Range: -40/+85°C
- X-Ref to Cypress, ISSI, Samsung
- Company: Taiwanese, fabless

PYRAMID

- Density: 64 b - 4 Mb
- V_{CC}: 5.0V +/- 10%
- Interface: x1, x4, x8, x16
- max. Temp. Range: -55/+125°C
- MIL-STD-883 compliant, SMDs
- Company: US based, fabless

WINBOND

- Density: 32 Mb - 512 Mb
- V_{CC}: 1.8V / 3V
- Interface: HyperBUS
- max. Temp. Range: -40/+85°C
- HyperRAM, low V_{CC} options on request
- Company: Taiwanese, own Fabs

EEPROM

FMD

- Density: 1 kb - 1 Mb
- V_{CC}: 1.8V - 5.5V
- Interface: SPI, I2C, 3-Wire
- max. Temp. Range: -40/+85°C
- V_{CC:min} = 1.7V on some devices available
- Company: Chinese, fabless

PYRAMID

- Density: 16 kb - 4 Mb
- V_{CC}: 5.0V +/- 10%
- Interface: Parallel
- max. Temp. Range: -55/+125°C
- MIL-STD-883 compliant, SMDs
- Company: US based, fabless

BYTE SEMICONDUCTOR

- Density: 2 kb - 2 Mb
- V_{CC}: 1.65V - 3.6V
- Interface: SPI, I2C
- max. Temp. Range: -40/+105°C
- KGD option
- Company: US based, fabless

